SCES395B-JULY 2002-REVISED OCTOBER 2005

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- DOC[™] Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ± 24 mA at 2.5-V V_{CC}
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.4-V to 3.6-V Power-Supply Range
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 16-bit (dual-octal) noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCA164245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCA164245 is designed so that the control pins (1DIR, 2DIR, $1\overline{OE}$, and $2\overline{OE}$) are supplied by V_{CCA} .

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CCA} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either V_{CC} input is at GND, then both ports are in the high-impedance state.

ORDERING INFORMATION

T _A	PACKA	GE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP - DGG	Tape and reel	SN74AVCA164245GR	AVCA164245
40°C to 95°C	TVSOP - DGV	Tape and reel	SN74AVCA164245VR	WA4245
–40°C to 85°C	VFBGA – GQL	Tape and reel	SN74AVCA164245KR	WA 4245
	VFBGA – ZQL	Tape and reel	74AVCA164245ZQLR	WA4245

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



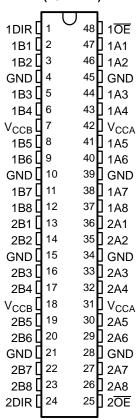
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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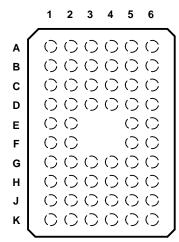


TERMINAL ASSIGNMENTS

DGG OR DGV PACKAGE (TOP VIEW)



GQL OR ZQL PACKAGE (TOP VIEW)



TERMINAL ASSIGNMENTS(1)

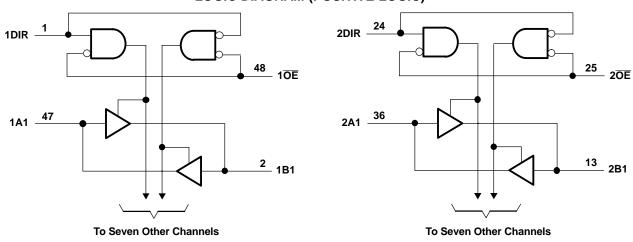
	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V _{CCB}	V _{CCA}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	V _{CCB}	V _{CCA}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 OE

(1) NC - No internal connection

FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION					
ŌĒ	DIR	OI ENATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	X	Isolation					

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DGG and DGV packages.



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CCA} V _{CCB}	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
V_{I}	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
M	Voltage range applied to any output	A port	-0.5	4.6	V
V _O	in the high-impedance or power-off state ⁽²⁾	B port	-0.5	4.6	V
.,	V-II	A port	-0.5 V ₀	_{CCA} + 0.5	
Vo	Voltage range applied to any output in the high or low state (2)(3)	B port	-0.5 V ₀	_{CCB} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current	<u>.</u>		±50	mA
	Continuous current through V _{CCA} , V _{CCB} , or GND			±100	mA
		DGG package		70	
θ_{JA}	Package thermal impedance (4)	DGV package	DGV package		°C/W
		GQL/ZQL package		42	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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Recommended Operating Conditions (1)(2)(3)

			V _{cci}	V _{cco}	MIN	MAX	UNIT
V_{CCA}	Supply voltage				1.4	3.6	V
V _{CCB}	Supply voltage				1.4	3.6	V
			1.4 V to 1.95 V		V _{CCI} × 0.65		
V_{IH}	High-level input voltage	Data inputs	1.95 V to 2.7 V		1.7		V
	input voltage		2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			$V_{CCI} \times 0.35$	
V_{IL}	Low-level input voltage	Data inputs	1.95 V to 2.7 V			0.7	V
	input voltage		2.7 V to 3.6 V			0.8	
			1.4 V to 1.95 V		V _{CCA} × 0.65		
V_{IH}	High-level input voltage	Control inputs (referenced to V _{CCA})	1.95 V to 2.7 V		1.7		V
	input voltage	(referenced to VCCA)	2.7 V to 3.6 V		2		
			1.4 V to 1.95 V			$V_{CCA} \times 0.35$	
V_{IL}	Low-level input voltage	Control inputs (referenced to V _{CCA})	1.95 V to 2.7 V			0.7	V
	- input voitage	(referenced to v _{CCA})	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
V	Output valtage	Active state			0	V _{cco}	V
Vo	Output voltage	3-state			0	3.6	V
				1.4 V to 1.6 V		-2	
	High lavel autout av			1.65 V to 1.95 V		-4	A
I _{OH}	High-level output cu	rrent		2.3 V to 2.7 V		-8	mA
				3 V to 3.6 V		-12	
				1.4 V to 1.6 V		2	
				1.65 V to 1.95 V		4	A
l _{OL}	Low-level output cur	rent		2.3 V to 2.7 V		8	mA
				3 V to 3.6 V		12	
Δt/Δν	Input transition rise	or fall rate				5	ns/V
T _A	Operating free-air te	mperature			-40	85	°C

 V_{CCI} is the V_{CC} associated with the input port. V_{CCO} is the V_{CC} associated with the output port. All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics (1)(2)

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CON	IDITIONS	V _{CCA}	V _{CCB}	MIN	TYP ⁽³⁾	MAX	UNIT
		$I_{OH} = -100 \mu A$,	$V_I = V_{IH}$	1.4 V to 3.6 V	1.4 V to 3.6 V	V _{CCO} - 0.2			
		$I_{OH} = -2 \text{ mA},$	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			
V_{OH}		$I_{OH} = -4 \text{ mA},$	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			V
		$I_{OH} = -8 \text{ mA},$	$V_{I} = V_{IH}$	2.3 V	2.3 V	1.75			
		$I_{OH} = -12 \text{ mA},$	$V_I = V_{IH}$	3 V	3 V	2.3			
		$I_{OH} = 100 \mu A$,	$V_I = V_{IL}$	1.4 V to 3.6 V	1.4 V to 3.6 V			0.2	
		$I_{OH} = 2 \text{ mA},$	$V_I = V_{IL}$	1.4 V	1.4 V			0.35	
V_{OL}		$I_{OH} = 4 \text{ mA},$	$V_I = V_{IL}$	1.65 V	1.65 V			0.45	V
		I _{OH} = 8 mA,	$V_I = V_{IL}$	2.3 V	2.3 V			0.55	
		I _{OH} = 12 mA,	$V_I = V_{IL}$	3 V	3 V			0.7	
I _I	Control inputs	$V_I = V_{CCA}$ or GND		1.4 V to 3.6 V	3.6 V			±2.5	μΑ
	A port	\\ a=\\\ \ 0.45.2.0.\\		0 V	0 to 3.6 V			±10	^
l _{off}	B port	V_I or $V_O = 0$ to 3.6 V		0 to 3.6 V	0 V			±10	μΑ
	A or B port		OE = V _{IH}	3.6 V	3.6 V			±12.5	
$I_{OZ}^{(4)}$	B port	$V_O = V_{CCO}$ or GND, $V_I = V_{IH}$ or V_{IL}	OE = don't care	0 V	3.6 V			±12.5	μΑ
	A port	T VI — VIH OI VIL	OE = don't care	3.6 V	0 V			±12.5	
				1.6 V	1.6 V			20	
				1.95 V	1.95 V			20	
		V – V or CND	1 - 0	2.7 V	2.7 V			30	^
I _{CCA}		$V_I = V_{CCI}$ or GND,	1 ₀ = 0	0 V	3.6 V			-40	μΑ
				3.6 V	0 V			40	
				3.6 V	3.6 V			40	
				1.6 V	1.6 V			20	
				1.95 V	1.95 V			20	
		$V_I = V_{CCI}$ or GND,	1 - 0	2.7 V	2.7 V			30	^
I _{CCB}		VI - VCCI OI GIAD,	10 = 0	0 V	3.6 V			40	μΑ
				3.6 V	0 V			-40	
				3.6 V	3.6 V			40	
Ci	Control inputs	V _I = 3.3 V or GND		3.3 V	3.3 V		4		pF
C _{io}	A or B port	$V_O = 3.3 \text{ V or GND}$		3.3 V	3.3 V		5		pF

 $[\]begin{array}{ll} \hbox{(1)} & V_{CCO} \text{ is the } V_{CC} \text{ associated with the output port.} \\ \hbox{(2)} & V_{CCI} \text{ is the } V_{CC} \text{ associated with the input port.} \\ \hbox{(3)} & \text{All typical values are at } T_A = 25^{\circ}\text{C.} \\ \hbox{(4)} & \text{For I/O ports, the parameter } I_{OZ} \text{ includes the input leakage current.} \\ \end{array}$

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Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.5 V \pm 0.1 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = ± 0.1		V _{CCB} = ± 0. 1	1.8 V 5 V	V _{CCB} = ± 0.2		V _{CCB} = ± 0.3		UNIT
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
4	Α	В	1.7	6.7	1.9	6.3	1.8	5.5	1.7	5.8	20
t _{pd}	В	А	1.8	6.8	2.2	7.4	2.1	7.6	2.1	7.3	ns
•	ŌĒ	А	2.6	8.4	2.7	8.2	2.3	6.3	2.1	5.6	ns
t _{en}	OL	В	2.7	8.6	3.2	10.2	3.2	10.8	3.2	10.7	115
	ŌĒ	Α	2.1	7	2.5	7	1.7	5.3	2	6.1	20
t _{dis}	OE .	В	2.1	7.1	2.5	7.1	2.1	6.5	2.1	6.4	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (see Figure 2)

PARAMETER	FROM	TO (OUTPUT)		V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V	
	(INPUT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Α	В	1.7	6.4	1.8	6	1.7	4.7	1.6	4.3	
t _{pd}	В	Α	1.4	5.5	1.8	6	1.8	5.8	1.8	5.5	ns
	ŌĒ	А	2.5	8	2.7	7.8	2.2	5.8	2	5.1	
t _{en}	OE .	В	1.8	6.7	2.7	7.8	2.7	8.1	2.7	8.1	ns
t _{dis}	t _{dis} OE	А	2.1	6.4	2.5	6.4	1.5	4.5	1.8	5	20
	OE .	В	2.1	6.6	2.5	6.4	2	5.5	2	5.5	ns

Switching Characteristics

over recommended operating free-air temperature range, $\rm V_{CCA}$ = 2.5 V \pm 0.2 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		UNIT	
	(INFOT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
+	Α	В	1.6	6	1.8	5.6	1.5	4	1.4	3.4	no	
t _{pd}	В	Α	1.3	4.6	1.7	4.4	1.5	4	1.4	3.7	ns	
	0-	Α	2.6	7.4	2.7	7.2	2.2	5.3	2	4.5		
t _{en}	ŌĒ	В	1.2	4.1	2.2	5.1	2.2	5.3	2.2	5.3	ns	
	OF.	is OE	A	2	5.7	2.3	5.7	1.4	3.7	1.6	4	
t _{dis}	OE	В	0.9	4.5	1.7	4.5	1.4	3.7	1.4	3.7	ns	



Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = ± 0 .1		V _{CCB} = ± 0. 1		V _{CCB} = ± 0.2		V _{CCB} = ± 0.3	3.3 V 3 V	UNIT
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
4	Α	В	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	5
t _{pd}	В	А	1.3	4.5	1.6	3.8	1.5	3.3	1.4	3.1	ns
4	ŌĒ	Α	2.5	7	2.6	6.9	2.1	5	1.9	4.1	5
t _{en}	OE	В	0.8	2.6	1.9	4	2	4.1	1.9	4.1	ns
4	ŌĒ	Α	1.2	5.4	2.2	5.2	1.2	3.3	1.5	3.6	
t _{dis}	OE .	В	1.2	5.4	1.7	4.4	1.5	3.6	1.5	3.6	ns

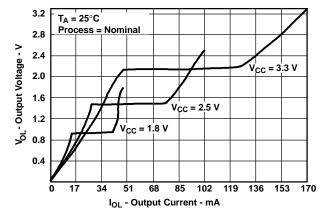
Operating Characteristics

 V_{CCA} and V_{CCB} = 3.3 V, T_A = 25°C

	PARAMETER		TEST C	CONDITIONS	TYP	UNIT
	Power dissipation capacitance per transceiver,	Outputs enabled			14	
	A-port input, B-port output	Outputs disabled	0 0	4 40 MH-	7	
C _{pdA}	Power dissipation capacitance per transceiver,	Outputs enabled	$C_L = 0$,	f = 10 MHz	20	pF
	B-port input, A-port output	Outputs disabled			7	
	Power dissipation capacitance per transceiver,	Outputs enabled			14	
0	A-port input, B-port output	Outputs disabled	0 0	4 40 MH-	7	_
C _{pdB}	Power dissipation capacitance per transceiver,	Outputs enabled	$C_L = 0$,	f = 10 MHz	20	pF
	B-port input, A-port output	Outputs disabled			7	

OUTPUT DESCRIPTION

The DOCTM circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOCTM) Circuitry Technology and Applications*, literature number SCEA009.



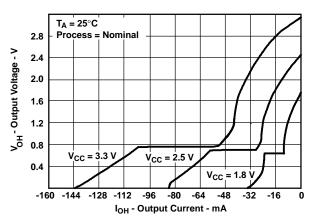
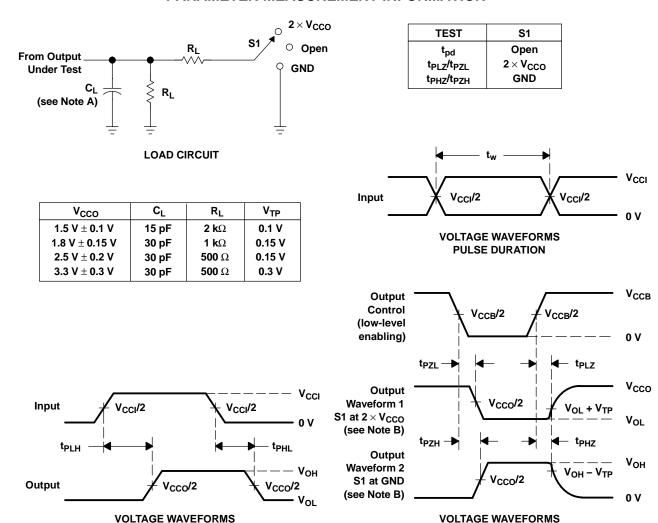


Figure 1. Output Voltage vs Output Current

ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω , $dv/dt \geq$ 1 V/ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. V_{CCI} is the V_{CC} associated with the input port.
 - I. V_{CCO} is the V_{CC} associated with the output port.

PROPAGATION DELAY TIMES

Figure 2. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

20-Feb-2021

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74AVCA164245GRE4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCA164245	Samples
74AVCA164245VRE4	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WA4245	Samples
SN74AVCA164245GR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCA164245	Samples
SN74AVCA164245VR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WA4245	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

20-Feb-2021

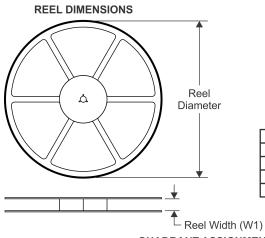
continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

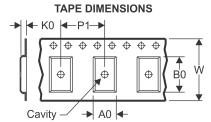
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 21-Feb-2021

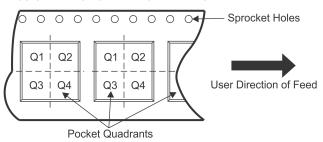
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

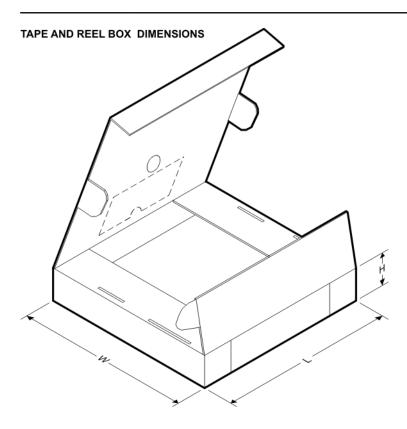
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCA164245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AVCA164245VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74AVCA164245GR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74AVCA164245VR	TVSOP	DGV	48	2000	853.0	449.0	35.0	

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

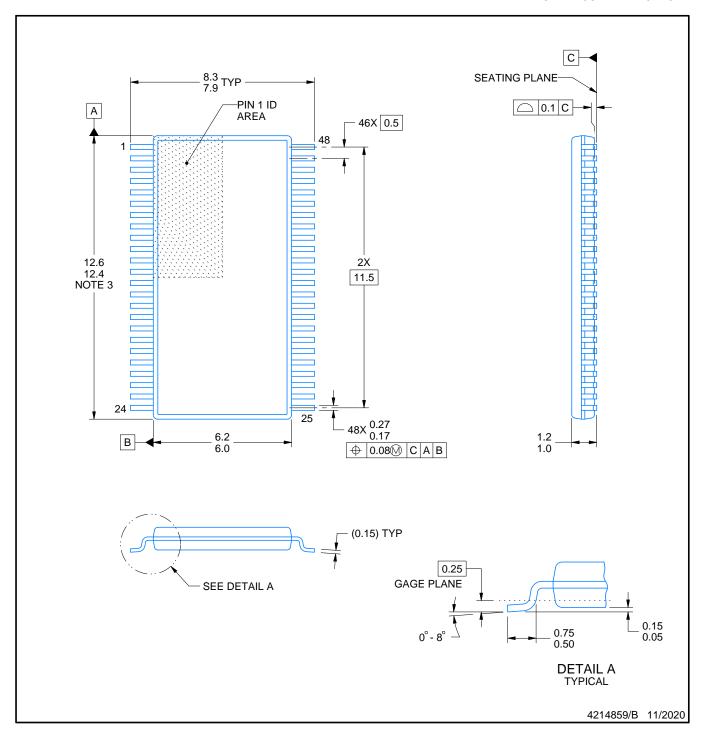
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



NOTES:

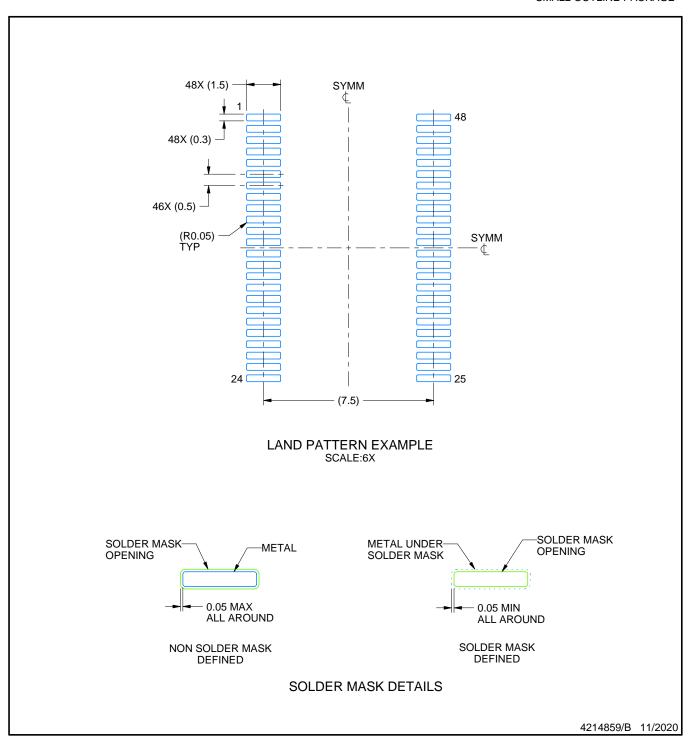
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

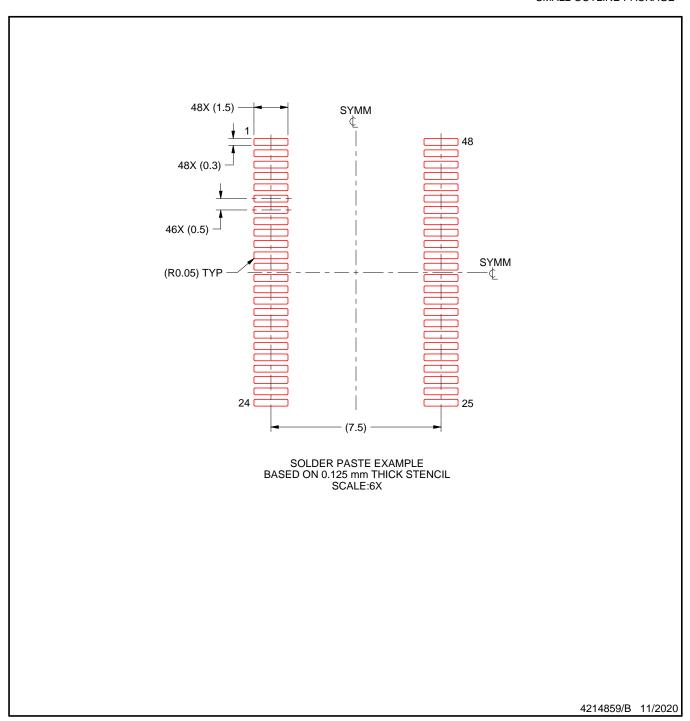


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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